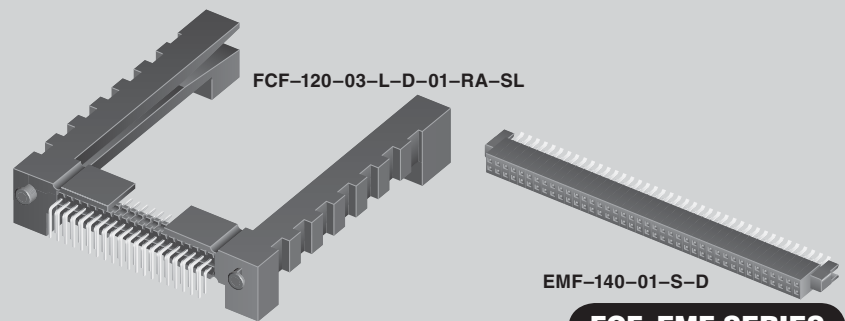




(1,27 mm) .050"

FCF, EMF SERIES

FLEXCARD™ TERMINAL & SOCKET STRIPS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?FCF or www.samtec.com?EMF

Insulator Material:
Black Liquid Crystal Polymer

Terminal Material (FCF):
Phosphor Bronze

Contact Material (EMF):
BeCu

Plating:
Sn or Au over

50μ" (1,27 μm) Ni

Operating Temp Range:
FCF = -55°C to +105°C Tin
FCF = -55°C to +125°C Gold
EMF = -55°C to +125°C

Contact Resistance (EMF):
10 mΩ

Insertion Depth (EMF):
(3,05 mm) .120" to
(4,06 mm) .160"

Insertion Force (EMF):
(Single contact only)
3.0 oz (0,83 N) avg.

Withdrawal Force (EMF):
(Single contact only)
2.0 oz (0,56 N) avg.

Lead-Free Solderable:
Yes

SMT Lead Coplanarity (EMF):
(0,10 mm) .004" max (20)
(0,15 mm) .006" max (30-50)

RoHS Compliant:
Yes

FCF - 1 NO. PINS PER ROW - LEAD STYLE - PLATING OPTION - D - CARD SLOT - TAIL OPTION - SL

Mates with: EMF

20, 30, 40 & 50
(Standard sizes)

Specify
LEAD
STYLE
from
chart

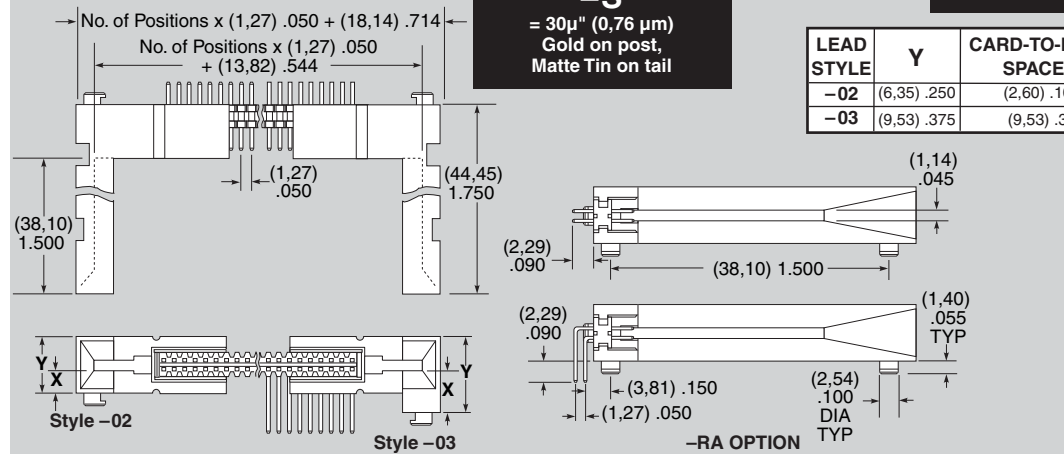
-L
= 10μ" (0,25 μm)
Gold on post,
Matte Tin on tail

-S
= 30μ" (0,76 μm)
Gold on post,
Matte Tin on tail

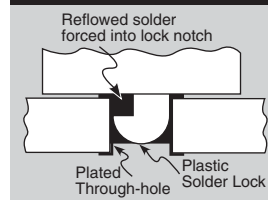
-01
= Accepts
(0,80 mm)
.031"
thick
card

-RA
= Right Angle
(Leave blank for
vertical version.
Style -02 only)

LEAD STYLE	Y	CARD-TO-BOARD SPACE (X)
-02	(6,35) .250	(2,60) .1025
-03	(9,53) .375	(9,53) .375



APPLICATIONS



RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



EMF - 1 NO. PINS PER ROW - CARD THICKNESS - PLATING OPTION - D

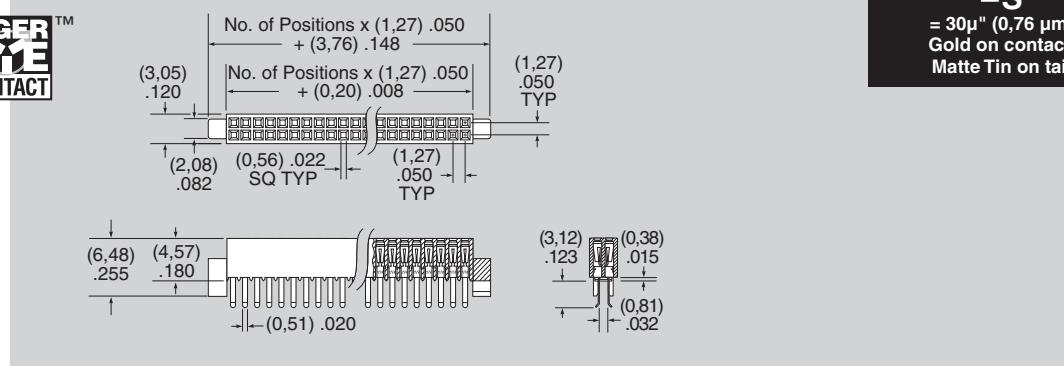
Mates with: FCF

20, 30, 40 & 50
(Standard sizes)

-01
= (0,80 mm) .031"
thick board

-L
= 10μ" (0,25 μm)
Gold on contact,
Matte Tin on tail

-S
= 30μ" (0,76 μm)
Gold on contact,
Matte Tin on tail



Note: Some lengths, styles and options are non-standard, non-returnable.

WWW.SAMTEC.COM

Due to technical progress, all designs, specifications and components are subject to change without notice.